



Kynar Flex® PPA grades as process aids for polyolefin resins designed for high volume resin production applications

Arkema presents two new Kynar Flex® grades used as process aids for polyolefin resins (LLDPE, HDPE, PP) suitable for many industrial applications including film extrusion, blow-moulding, and pipe extrusion. These grades are specifically designed for high throughput resin production.

Kynar Flex® PPA fluoropolymer based products are incorporated into polyolefin resins as additives, at very low concentration, of the order of 0.015%-0.08% (150-800ppm), depending on the application. This low concentration is sufficient to bring considerable improvements to the manufacturing process, in terms of both quality of finished product and processing conditions.

Continuously developing its Kynar Flex® PPA range for use as process aids for polyolefin resins, Arkema has now enhanced its range with two new grades, Kynar Flex® 8600 and Kynar Flex® 8601. These products are aimed more specifically at high volume resin production applications, in which the performance vs cost ratio is of prime importance. Both grades are available either as a compacted pellet or as a free-flowing powder, to suit every market requirement.

These products now further enhance Arkema's existing wide range of PPA products, which includes:

- the widely accepted Kynar Flex® 5300 and Kynar Flex® 5301 grades that achieve exceptionally high efficiency even in very tough systems containing other well-known antagonistic additives and fillers
- Kynar Flex® 3121-50 and Kynar Flex® 2821, which can be used when high thermal stability is required.

Finished products manufactured using Kynar Flex® PPA are free of "shark-skin" surface defects, while combining superior film transparency and mechanical properties. Kynar Flex® PPA improves the smoothness and surface finish of pipes, and the surface gloss of blow-moulded parts.

In terms of process improvements, Kynar Flex® PPA helps increase processing speed while reducing energy consumption, processing temperature and pressure. It also significantly reduces die-buildup, hence minimizing downtime.